



Features

- For High Speed Circuits
- Surface mount EMI suppression components
- Nickel barrier termination for excellent resistance to solder heat
- Wide range of impedance values
- Multilayer Technology
- Flow and reflow soldering

Electrical

Impedance Range: 7 to 2700Ω

Tolerance: 25% over entire range

Operating Temp: -55°C ~ +125°C

Storage Temp: -5°C to 40°C at 40~70% Humidity, before PCB assembly. -55°C to +125°C after PCB assembly.

Rated Current Based on temp rise not to exceed 30°C

Resistance to Solder Heat

Pre-Heat 150°C, 1 minute

Solder Composition: Sn/Ag3.0/Cu0.5

Solder Temp: 260±5°C for 10sec ±1 sec.

Minimum of 75% of Electrode covered with new solder.

Impedance within 30% of initial value.

Test Equipment

(Z): HP4291A RF Impedance/Material Analyzer

(RDC): Chen Hwa 502BC

Physical

Packaging: 4000 per 7 inch reel.

Marking: None

Allied Part Number	Impedance (Ω) @ 100 MHz, 200mV	DC Resistance (Ω) Max.	Rated Current (mA)
HSB10			
HSB10-070-RC	7	0.1	600
HSB10-090-RC	9	0.1	600
HSB10-110-RC	11	0.1	600
HSB10-120-RC	12	0.1	600
HSB10-150-RC	15	0.1	600
HSB10-170-RC	17	0.1	600
HSB10-190-RC	19	0.1	600
HSB10-260-RC	26	0.1	600
HSB10-280-RC	28	0.1	600
HSB10-300-RC	30	0.1	600
HSB10-320-RC	32	0.1	600
HSB10-330-RC	33	0.1	500
HSB10-400-RC	40	0.1	500
HSB10-500-RC	50	0.1	500
HSB10-520-RC	52	0.15	500
HSB10-600-RC	60	0.15	500
HSB10-700-RC	70	0.15	500
HSB10-750-RC	75	0.15	500
HSB10-800-RC	80	0.15	500
HSB10-950-RC	95	0.15	500
HSB10-101-RC	100	0.25	300
HSB10-121-RC	120	0.25	300
HSB10-151-RC	150	0.25	300
HSB10-181-RC	180	0.3	300
HSB10-201-RC	200	0.3	300
HSB10-221-RC	220	0.3	300
HSB10-301-RC	300	0.3	300
HSB10-331-RC	330	0.3	300
HSB10-401-RC	400	0.3	300
HSB10-471-RC	470	0.4	300
HSB10-501-RC	500	0.4	300
HSB10-601-RC	600	0.4	300
HSB10-681-RC	680	0.4	300
HSB10-751-RC	750	0.5	200
HSB10-102-RC	1000	0.5	200
HSB10-152-RC	1500	0.6	200
HSB10-202-RC	2000	0.7	200
HSB10-222-RC	2200	0.8	200
HSB10-252-RC	2500	0.8	200
HSB10-272-RC	2700	1.5	100

All specifications subject to change without notice.